DOUBLE BUMPING OF FLEXIBLE SUBSTRATE FOR FIRST AND SECOND LEVEL INTERCONNECTS

ABSTRACT OF THE DISCLOSURE

An apparatus and method for improving the yield and reducing the cost of forming a semiconductor device assembly. An interposer substrate is formed with interconnections in the form of conductive bumps on both a first surface and a second surface to provide a respective first level interconnect and a second level interconnect for a semiconductor die to be mounted to the interposer substrate. The conductive bumps and conductive elements may be formed simultaneously by a plating process. The conductive bumps on the first surface are arranged to correspond with bond pads of a semiconductor die for the first level interconnect. The conductive bumps on the second surface are configured to correspond with a terminal pad pattern of a carrier substrate or other higher-level packaging.

[Figure 3]